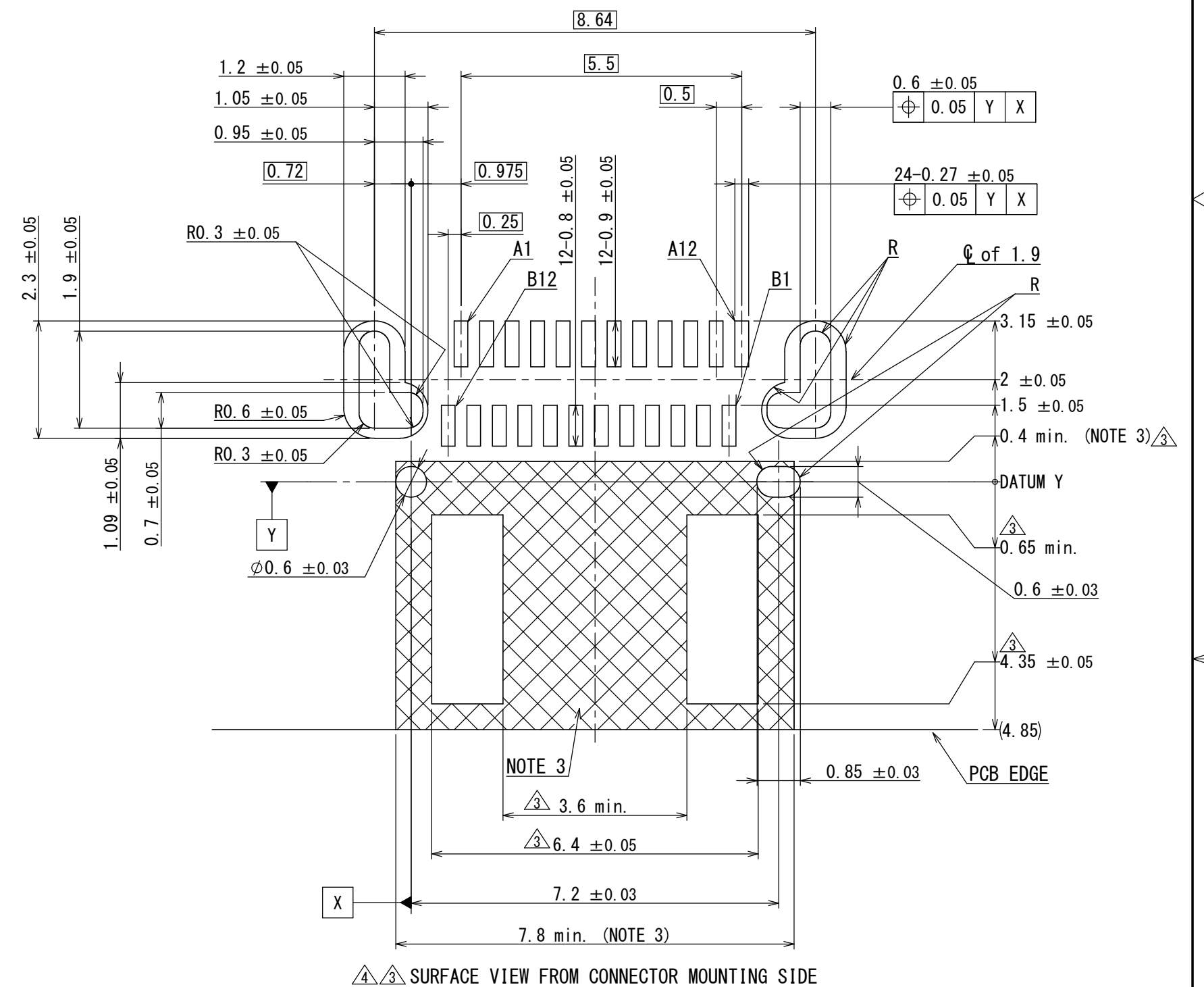
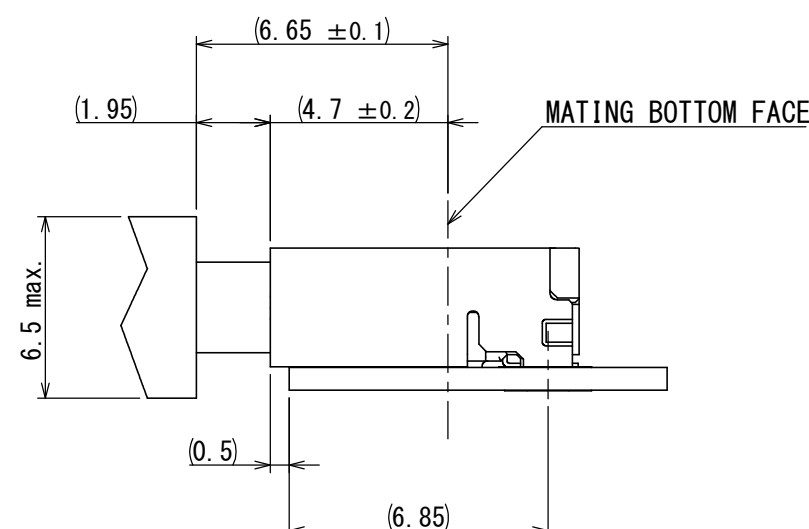
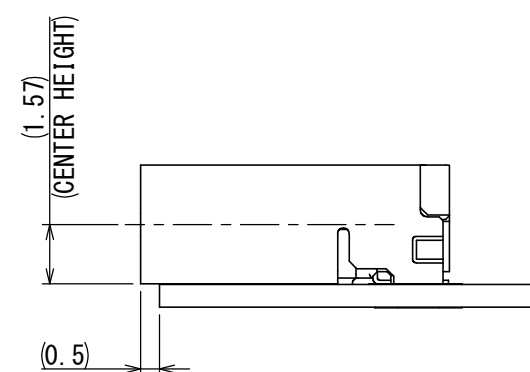
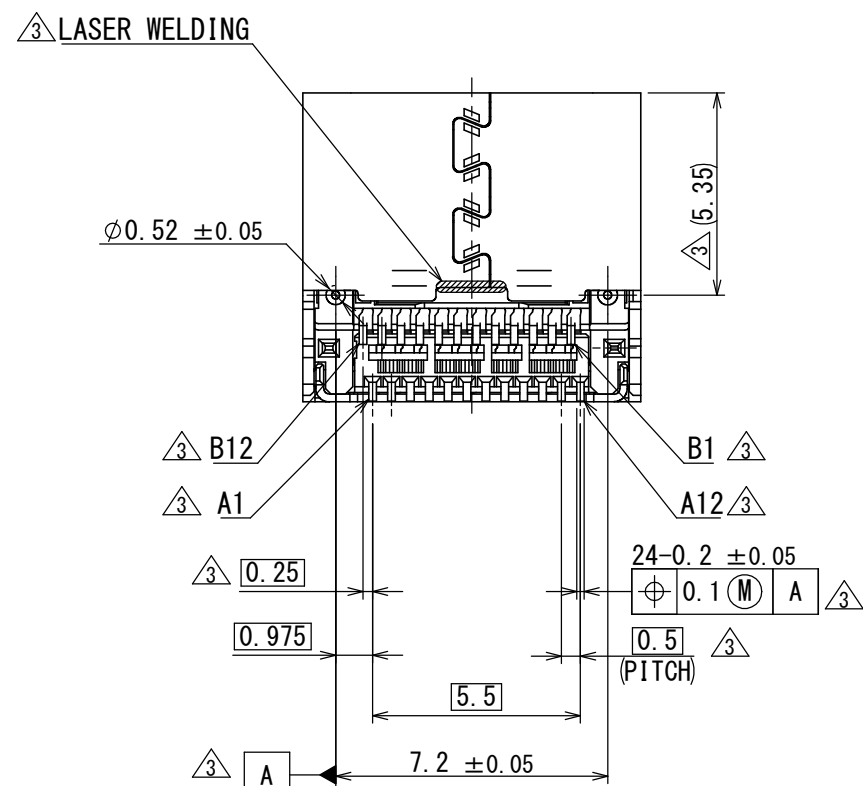
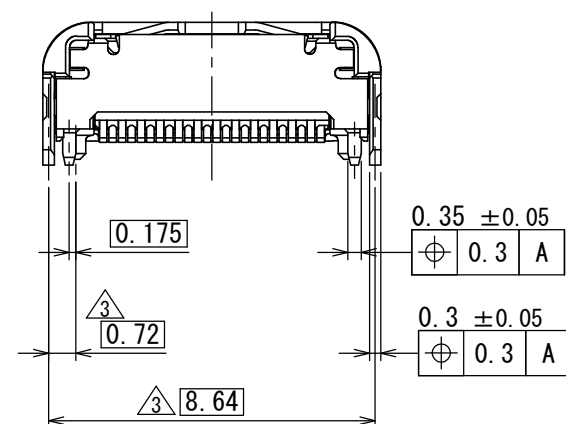
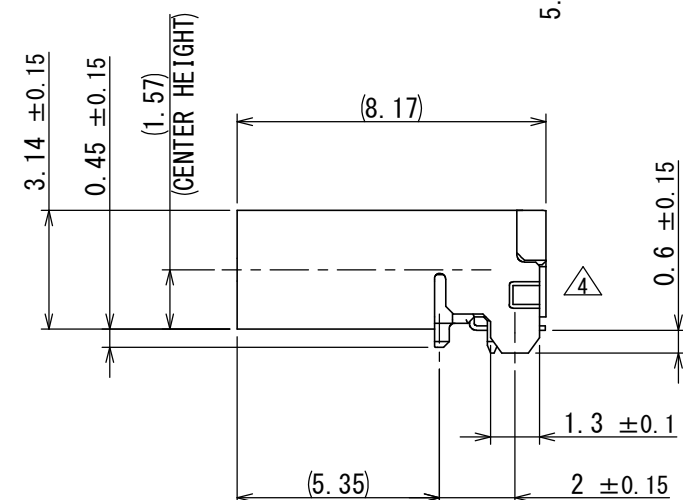
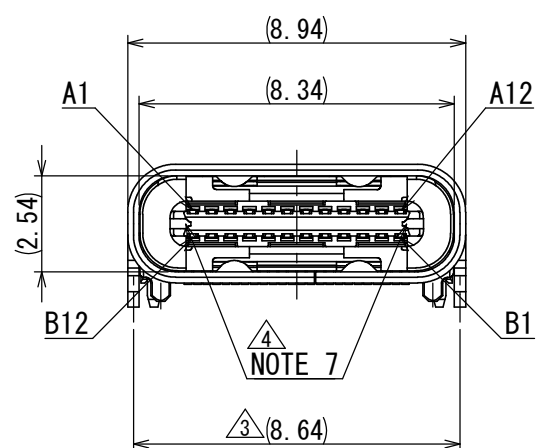
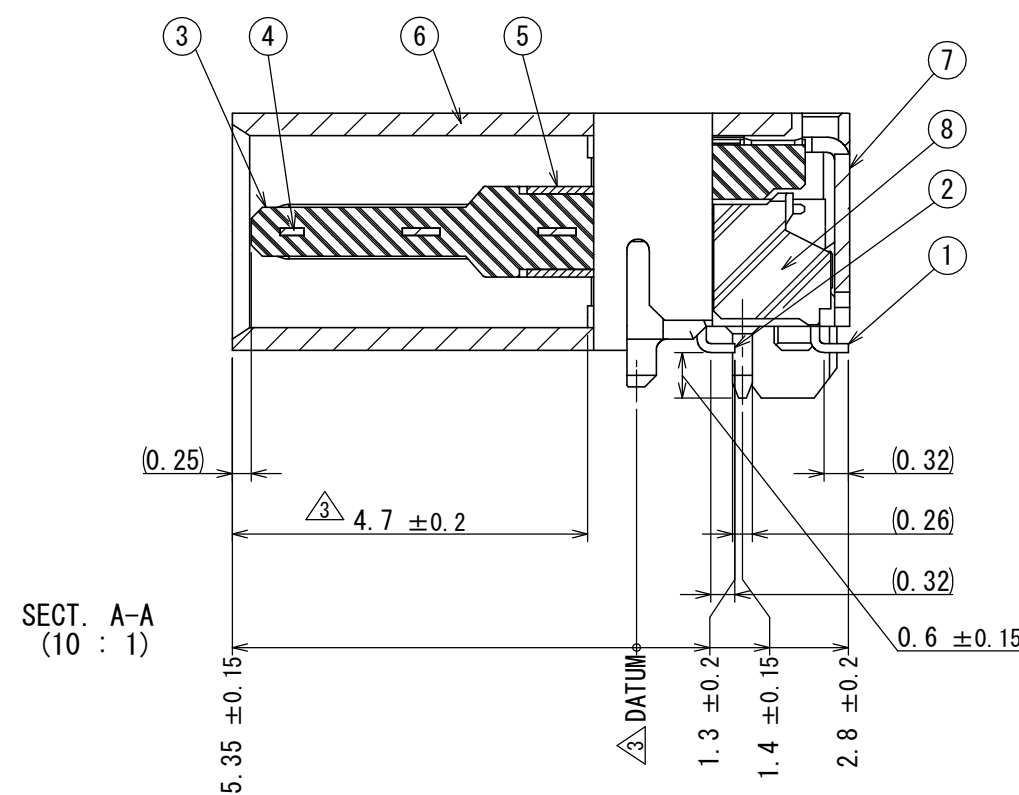
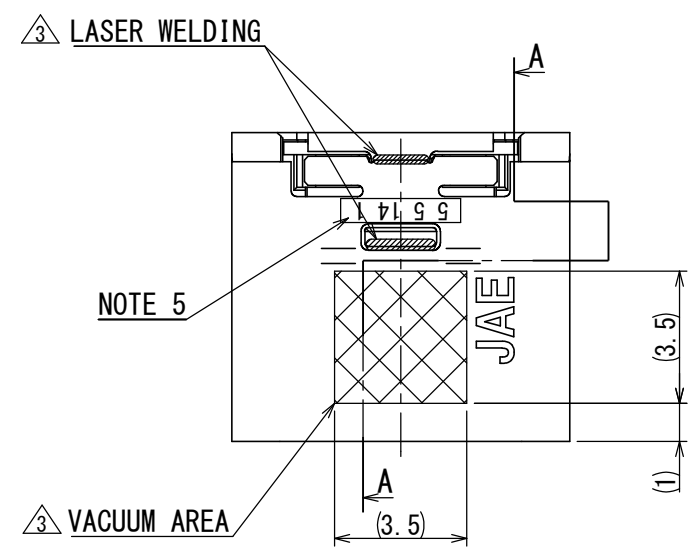


版数 VER.	年月日 D A T E	CN NO.	変更内容 DESCRIPTION	製 国 DR.	担当 CHK.	査 閲 APPD.	承認 APPD.
2	25/JUN/15	013535	CORRECT AN ERROR	K. SAITOU	K. UEDA	—	Y. SAITOU
3	07/JAN/2016	015856	ADDED NOTE etc.		K. SAITOU	—	Y. SAITOU
4	03/AUG/2016	018306	ADDED NOTE etc.		K. SAITOU	K. UEDA	Y. SAITOU



NOTE 1. THIS PRODUCT IS HALOGEN-FREE PRODUCT.
NOTE 2. COPLANARITY OF SMT TERMINAL IS 0.1 MAX.
NOTE 3. NO PCB ROUTING ALLOWED IN THIS AREA.
NOTE 4. THE SHELL LENGTH IS LESS THAN THE MINIMUM REFERENCES IN THE USB TYPE C STANDARD.
AS SUCH THE SYSTEM IMPLEMENTER IS RESPONSIBLE FOR ACHIEVING PRODUCT RELIABILITY.
THAT THE CONNECTOR BE MOUNTED SUCH THAT ALL FUNCTIONAL USB REQUIREMENTS ARE MET.
NOTE 5. LOT NUMBER IS MARKED AS INDICATED.




(EX) 5 5 14 1 YEAR (END OF ONE DIGIT AT CHRISTIAN ERA)
MONTH (JAN. TO SEP. :1 TO 9, OCT. :0, NOV. :X, DEC. :Y)
DAY (TWO-DIGITS NUMBER)
EQUIPMENT No. (NUMBER OR ALPHABET)

3 NOTE 6. PIN ASSIGNMENT (FRONT VIEW)

Pin No.	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
	GND	TX1+	TX1-	V _{BUS}	CC1	D+	D-	SBU1	V _{BUS}	RX2-	RX2+	GND
	GND	RX1+	RX1-	V _{BUS}	SBU2	D-	D+	CC2	V _{BUS}	TX2-	TX2+	GND
Pin No.	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

4 NOTE 7. METAL EXPOSED AREA SIZE COULD BE SLIGHTLY CHANGED BASED ON MOLING PROCESS CONDITION IN EACH LOT, HOWEVER THIS WOULD NOT AFFECT CONNECTOR FUNCTION.

8	INSULATOR 2	1	HEAT RESISTING PLASTIC	COLOR:BLACK	
7	REAR SHIELD	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS : 0.8 μ m MIN. \triangle ₄
6	SHELL	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS : 0.8 μ m MIN. \triangle ₄
5	GND PLATE	2	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS : 0.8 μ m MIN. \triangle ₄
4	MID PLATE	1	STAINLESS STEEL	NICKEL PLATING	PLATING THICKNESS : 0.8 μ m MIN. \triangle ₄
3	INSULATOR 1	1	HEAT RESISTING PLASTIC	COLOR:BLACK	
2	CONTACT B	12	COPPER ALLOY	CONTACT AREA GOLD FLASH OVER PALLADIUM-NICKEL OVER NICKEL \triangle ₄	PALLADIUM-NICKEL:0.75 μ m MIN. \triangle ₄
1	CONTACT A	12	COPPER ALLOY	SOLDER TALES GOLD FLASH OVER NICKEL	GOLD FLASH CONTACT AREA:0.05 μ m MIN. SOLDER TALES:0.03 μ m MIN.
符号	名称	数量	材料	仕上	備考

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
仕様書 (SPECIFICATION)			第1版 (ORIGINAL DATE)	尺度 (SCALE)	シリーズ (SERIES)
JACS-30353			14/MAY/2015	5:1	DX07
JAH1-30353-1 			製図 DR.	名称 (TITLE)	日本航空電子工業株式会社
一般公差 (GENERAL TOLERANCE)			担当 CHK.	DX07S024JJ1	 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
寸法 (DIMENSION)		角度 (ANGLES)	査閲 APPD.		
± 0.8		×° ±	—		
× ± 0.4		××° ±	承認 APPD.		
×× ± 0.1			Y. SAITOU		
単位 (UNIT) : mm			質量 (MASS)		図面番号 (DRAWING NO.)
××× ×					SJ115848